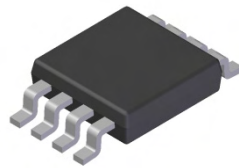


Features

- Low On-Resistance
 - 30mΩ @ $V_{GS} = 10V$
 - 40mΩ @ $V_{GS} = 4.5V$
 - 63mΩ @ $V_{GS} = 2.5V$
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 2)**
- **"Green" Device (Note 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

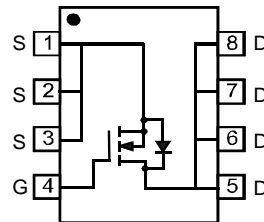
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.072 grams (approximate)



TOP VIEW

SO-8


 TOP VIEW
Internal Schematic

Maximum Ratings @ $T_A = 25^\circ C$ unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	± 12	V
Drain Current (Note 1)	Steady State	$T_A = 25^\circ C$	I_D	7.1	A
		$T_A = 70^\circ C$		5.7	
Pulsed Drain Current (Note 3)			I_{DM}	28	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P_D	2.5	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	50	$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Electrical Characteristics @ $T_A = 25^\circ C$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	—	—	± 80	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
		—	—	± 800		$V_{GS} = \pm 19V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	$V_{GS(th)}$	0.62	0.9	1.2	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	24	30	mΩ	$V_{GS} = 10V, I_D = 7.1A$
		—	30	40		$V_{GS} = 4.5V, I_D = 6.4A$
		—	50	63		$V_{GS} = 2.5V, I_D = 5.0A$
Forward Transconductance	g_{fs}	—	10	—	S	$V_{DS} = 5V, I_D = 5.1A$
Diode Forward Voltage (Note 5)	V_{SD}	—	0.78	1.16	V	$V_{GS} = 0V, I_S = 2.1A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	—	555	—	pF	$V_{DS} = 5V, V_{GS} = 0V$ $f = 1.0MHz$
Output Capacitance	C_{OSS}	—	109	—	pF	
Reverse Transfer Capacitance	C_{RSS}	—	82	—	pF	

- Notes:
1. Device mounted on 2 oz copper pad layout with $R_{\theta JA} = 50^\circ C/W$.
 2. No purposefully added lead.
 3. Pulse width $\leq 10\mu S$, Duty Cycle $\leq 1\%$.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Short duration pulse test used to minimize self-heating effect.

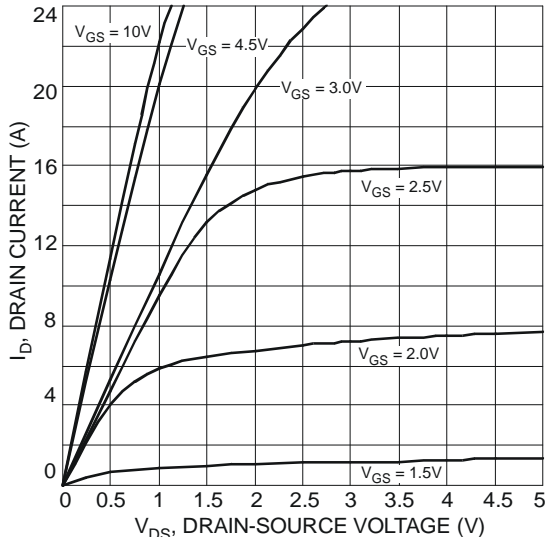


Fig. 1 Typical Output Characteristics

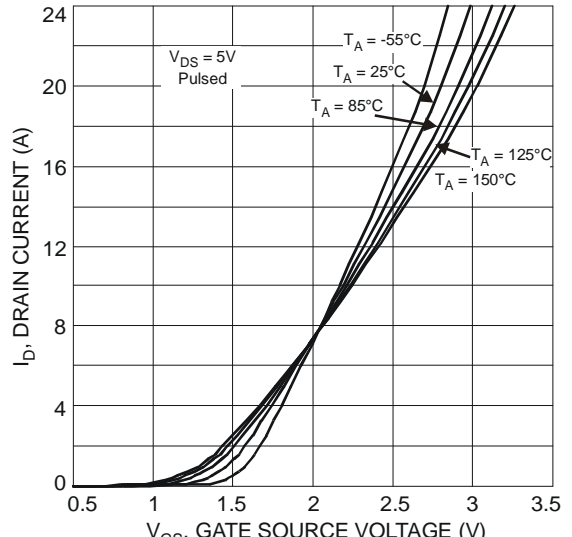


Fig. 2 Typical Transfer Characteristics

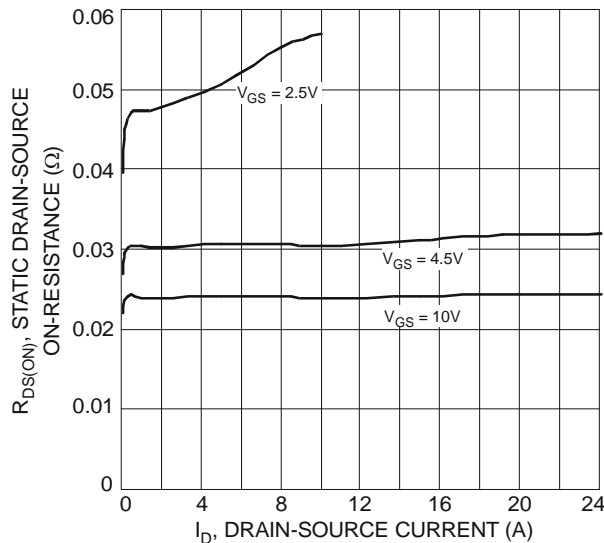


Fig. 3 On-Resistance vs. Drain Current & Gate Voltage

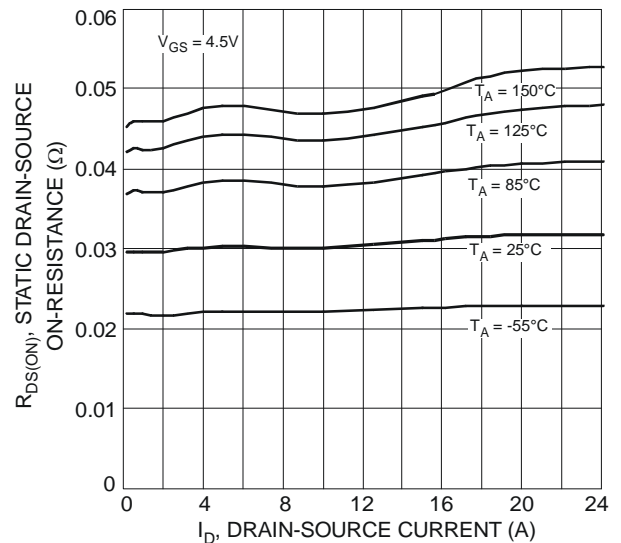


Fig. 4 On-Resistance vs. Drain Current & Temperature

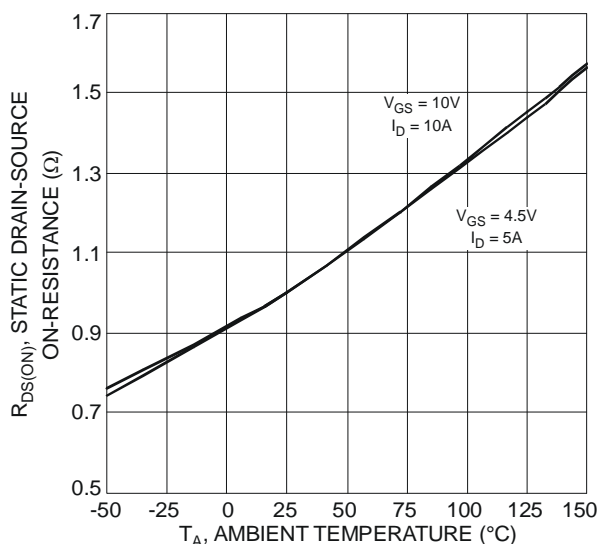


Fig. 5 Static Drain-Source On-Resistance vs. Ambient Temperature

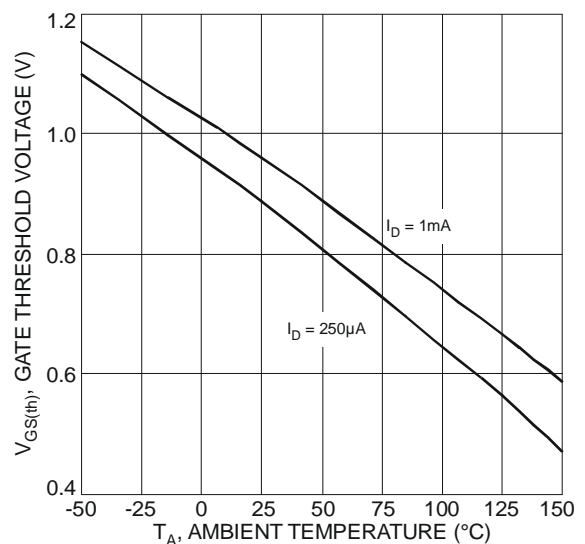


Fig. 6 Gate Threshold Variation vs. Ambient Temperature

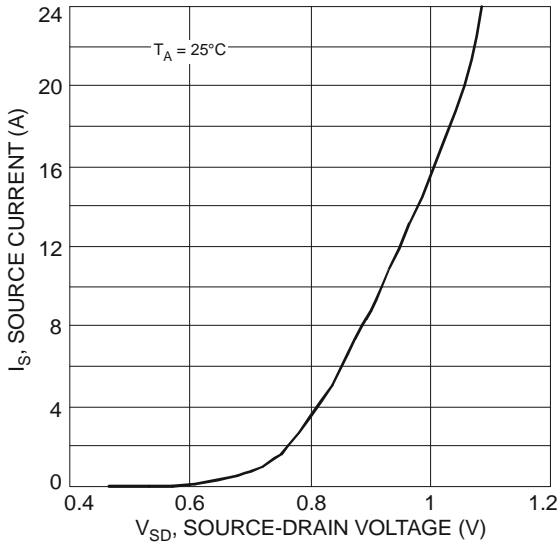


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

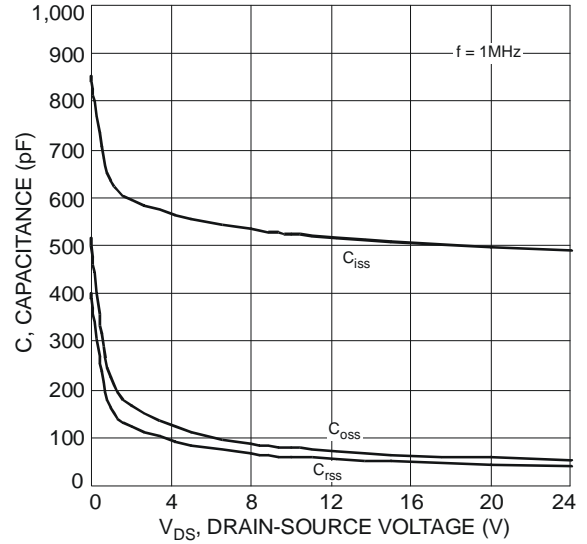


Fig. 8 Typical Total Capacitance

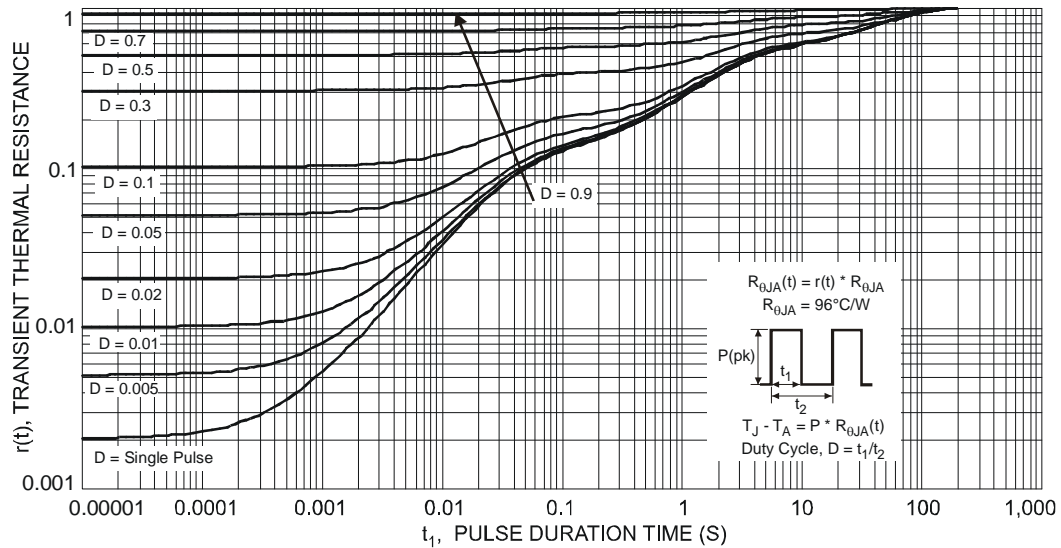


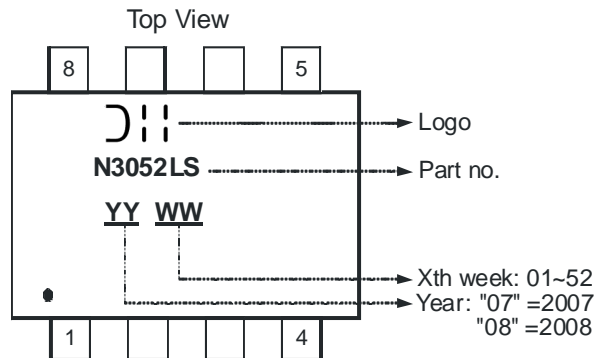
Fig. 9 Transient Thermal Resistance

Ordering Information (Note 6)

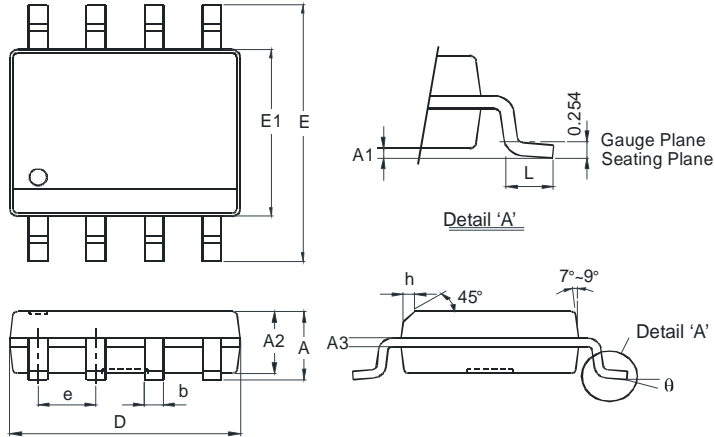
Part Number	Case	Packaging
DMN3052LSS-13	SO-8	2500/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

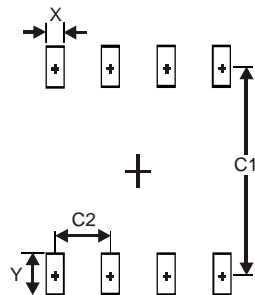


Package Outline Dimensions



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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